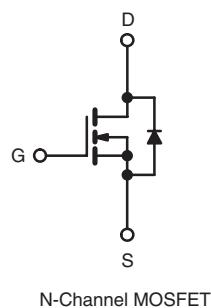
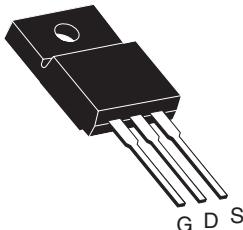


Power MOSFET

PRODUCT SUMMARY		
V_{DS} (V)	200	
$R_{DS(on)}$ (Ω)	$V_{GS} = 5.0$ V	0.40
Q_g (Max.) (nC)	40	
Q_{gs} (nC)	5.5	
Q_{gd} (nC)	24	
Configuration	Single	

TO-220 FULLPAK


FEATURES

- Isolated Package
- High Voltage Isolation = 2.5 kV_{RMS} ($t = 60$ s; $f = 60$ Hz)
- Sink to Lead Creepage Distance = 4.8 mm
- Logic-Level Gate Drive
- $R_{DS(on)}$ Specified at $V_{GS} = 4$ V and 5 V
- Fast Switching
- Ease of paralleling
- Lead (Pb)-free Available



DESCRIPTION

Third generation Power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220 FULLPAK eliminates the need for additional insulating hardware in commercial-industrial applications. The molding compound used provides a high isolation capability and a low thermal resistance between the tab and external heatsink. This isolation is equivalent to using a 100 micron mica barrier with standard TO-220 product. The FULLPAK is mounted to a heatsink using a single clip or by a single screw fixing.

ORDERING INFORMATION

Package	TO-220 FULLPAK
Lead (Pb)-free	IRLI630GPbF SiHLI630G-E3
SnPb	IRLI630G SiHLI630G

ABSOLUTE MAXIMUM RATINGS $T_C = 25$ °C, unless otherwise noted

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V_{DS}	200	
Gate-Source Voltage	V_{GS}	± 10	V
Continuous Drain Current	V_{GS} at 5.0 V	I_D	A
		$T_C = 25$ °C	
Pulsed Drain Current ^a	I_{DM}	6.2	
		$T_C = 100$ °C	
Linear Derating Factor		3.9	
Single Pulse Avalanche Energy ^b	E_{AS}	25	mJ
Repetitive Avalanche Current ^a	I_{AR}	6.2	A
Repetitive Avalanche Energy ^a	E_{AR}	3.5	mJ
Maximum Power Dissipation	P_D	35	W
Peak Diode Recovery dV/dt ^c	dV/dt	5.0	V/ns
Operating Junction and Storage Temperature Range	T_J, T_{stg}	- 55 to + 150	°C
Soldering Recommendations (Peak Temperature)	for 10 s	300 ^d	
Mounting Torque	6-32 or M3 screw	10	lbf · in
		1.1	N · m

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).

b. $V_{DD} = 25$ V, starting $T_J = 25$ °C, $L = 2.4$ mH, $R_G = 25$ Ω , $I_{AS} = 6.2$ A (see fig. 12).

c. $I_{SD} \leq 9.0$ A, $dI/dt \leq 120$ A/ μ s, $V_{DD} \leq V_{DS}$, $T_J \leq 150$ °C.

d. 1.6 mm from case.

* Pb containing terminations are not RoHS compliant, exemptions may apply

THERMAL RESISTANCE RATINGS

PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R_{thJA}	-	65	$^{\circ}\text{C}/\text{W}$
Maximum Junction-to-Case (Drain)	R_{thJC}	-	3.6	

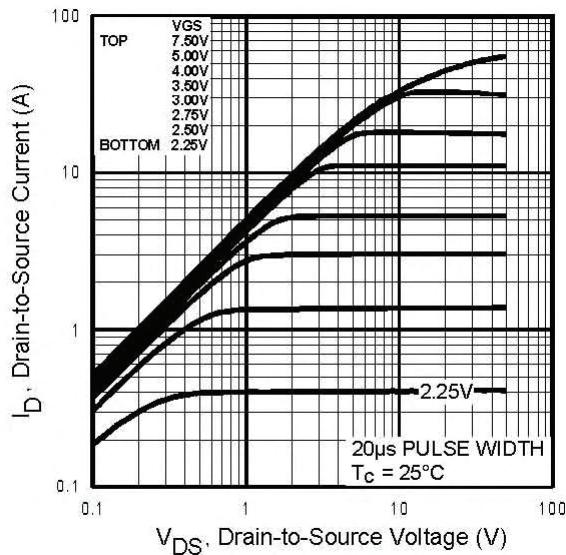
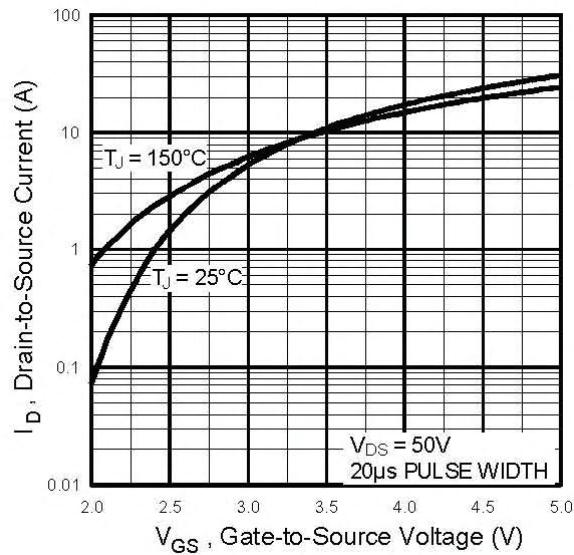
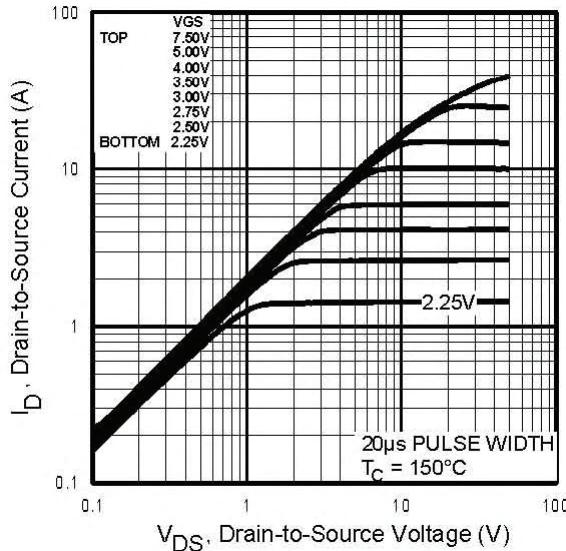
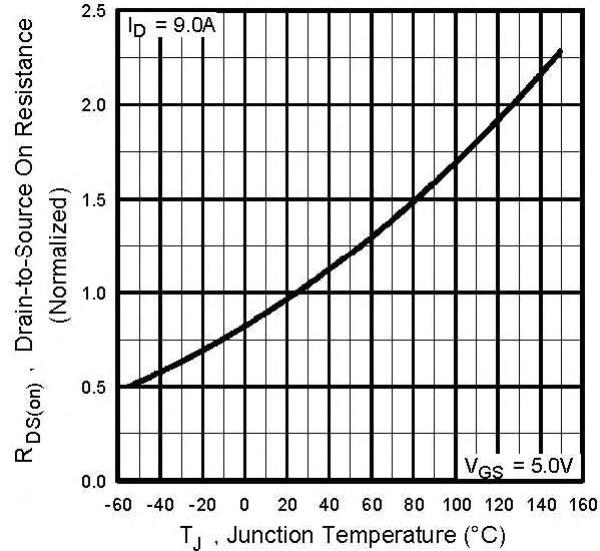
SPECIFICATIONS $T_J = 25^{\circ}\text{C}$, unless otherwise noted

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT	
Static								
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}$, $I_D = 250 \mu\text{A}$		200	-	-	V	
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to 25°C , $I_D = 1 \text{ mA}$		-	0.27	-	$^{\circ}\text{C}/\text{C}$	
Gate-Source Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}$, $I_D = 250 \mu\text{A}$		1.0	-	2.0	V	
Gate-Source Leakage	I_{GSS}	$V_{GS} = \pm 10 \text{ V}$		-	-	± 100	nA	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 200 \text{ V}$, $V_{GS} = 0 \text{ V}$		-	-	25	μA	
		$V_{DS} = 160 \text{ V}$, $V_{GS} = 0 \text{ V}$, $T_J = 125^{\circ}\text{C}$		-	-	250		
Drain-Source On-State Resistance	$R_{DS(\text{on})}$	$V_{GS} = 5.0 \text{ V}$	$I_D = 3.7 \text{ A}^b$	-	-	0.40	Ω	
		$V_{GS} = 4.0 \text{ V}$	$I_D = 3.1 \text{ A}^b$	-	-	0.50		
Forward Transconductance	g_{fs}	$V_{DS} = 50 \text{ V}$, $I_D = 5.4 \text{ A}^b$		4.8	-	-	S	
Dynamic								
Input Capacitance	C_{iss}	$V_{GS} = 0 \text{ V}$, $V_{DS} = 25 \text{ V}$, $f = 1.0 \text{ MHz}$, see fig. 5		-	1100	-	pF	
Output Capacitance	C_{oss}			-	220	-		
Reverse Transfer Capacitance	C_{rss}			-	70	-		
Total Gate Charge	Q_g	$V_{GS} = 10 \text{ V}$	$I_D = 9.0 \text{ A}$, $V_{DS} = 160 \text{ V}$, see fig. 6 and 13 ^b	-	-	40	nC	
Gate-Source Charge	Q_{gs}			-	-	5.5		
Gate-Drain Charge	Q_{gd}			-	-	24		
Turn-On Delay Time	$t_{d(\text{on})}$			-	8.0	-		
Rise Time	t_r	$V_{DD} = 100 \text{ V}$, $I_D = 9.0 \text{ A}$, $R_G = 6.0 \Omega$, $R_D = 11 \Omega$, see fig. 10 ^b		-	57	-	ns	
Turn-Off Delay Time	$t_{d(\text{off})}$			-	38	-		
Fall Time	t_f			-	33	-		
Internal Drain Inductance	L_D			-	4.5	-	nH	
Internal Source Inductance	L_S	Between lead, 6 mm (0.25") from package and center of die contact		-	7.5	-		
Drain-Source Body Diode Characteristics								
Continuous Source-Drain Diode Current	I_S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	6.2	A	
Pulsed Diode Forward Current ^a	I_{SM}			-	-	25		
Body Diode Voltage	V_{SD}	$T_J = 25^{\circ}\text{C}$, $I_S = 6.2 \text{ A}$, $V_{GS} = 0 \text{ V}^b$		-	-	2.0	V	
Body Diode Reverse Recovery Time	t_{rr}	$T_J = 25^{\circ}\text{C}$, $I_F = 9.0 \text{ A}$, $dI/dt = 100 \text{ A}/\mu\text{s}^b$		-	230	350	ns	
Body Diode Reverse Recovery Charge	Q_{rr}			-	1.7	2.6	μC	
Forward Turn-On Time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L_S and L_D)						

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).

b. Pulse width $\leq 300 \mu\text{s}$; duty cycle $\leq 2\%$.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

Fig. 1 - Typical Output Characteristics, $T_c = 25^\circ\text{C}$

Fig. 3 - Typical Transfer Characteristics

Fig. 2 - Typical Output Characteristics, $T_c = 150^\circ\text{C}$

Fig. 4 - Normalized On-Resistance vs. Temperature

IRLI630G, SiHLI630G

Vishay Siliconix

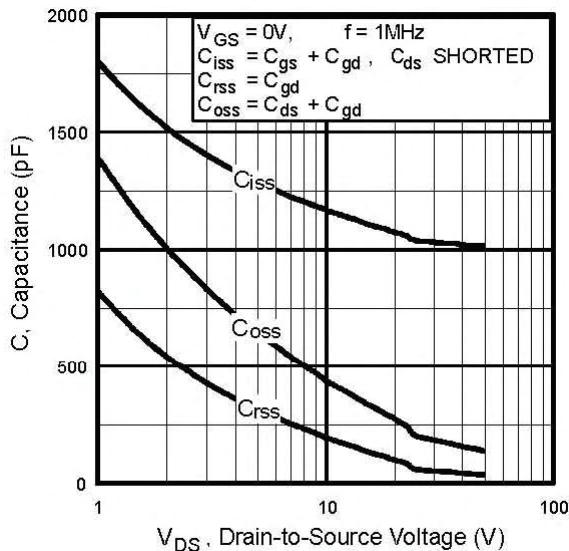


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

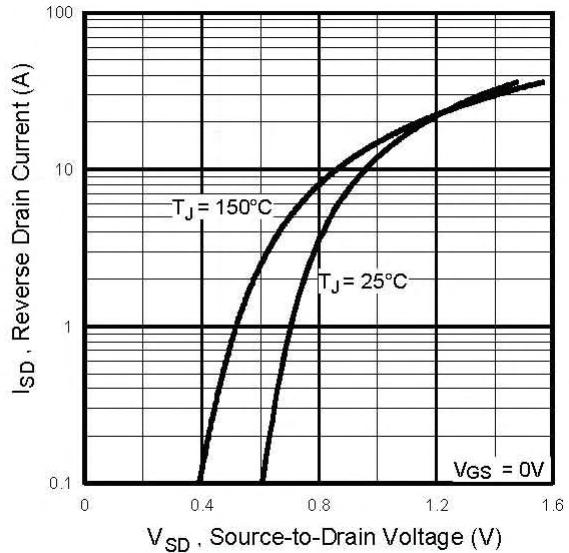


Fig. 7 - Typical Source-Drain Diode Forward Voltage

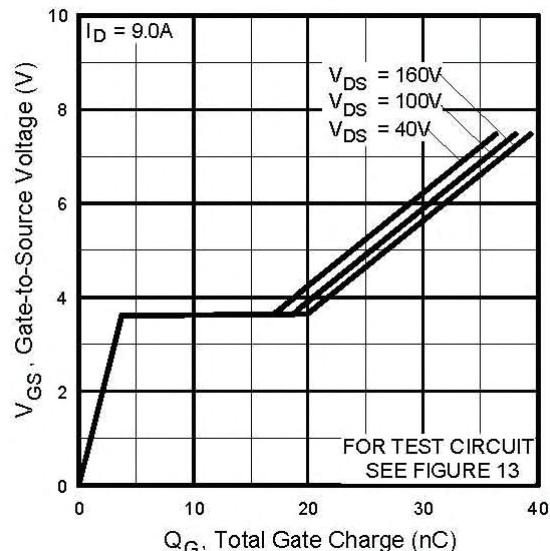


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

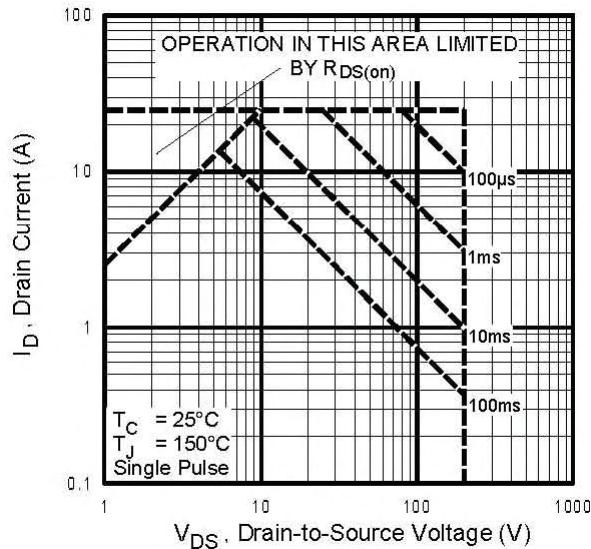
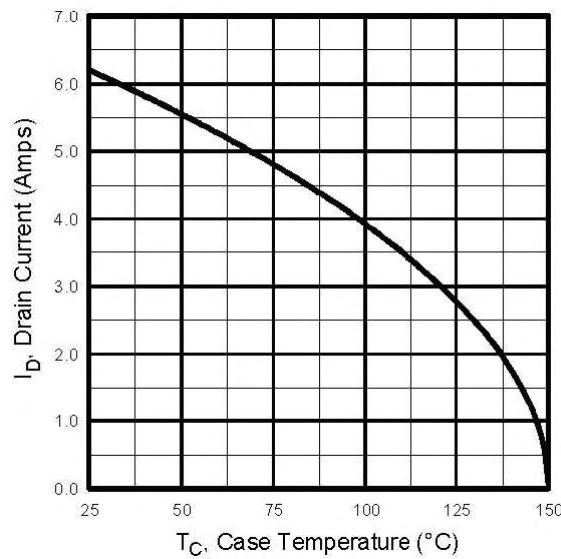
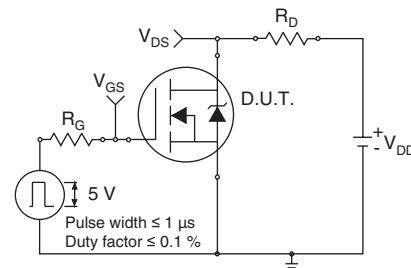
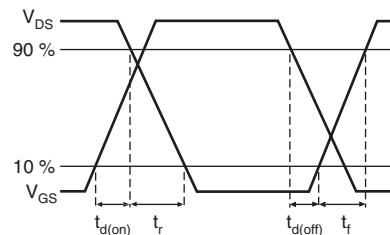
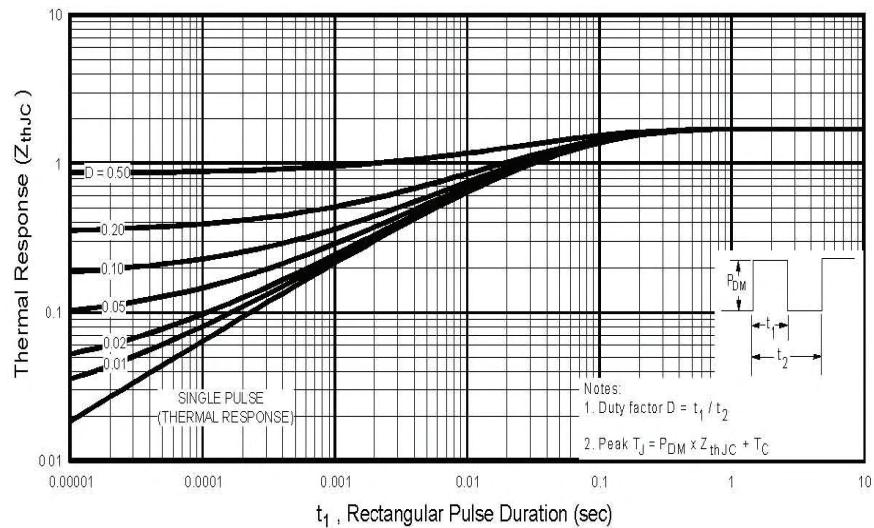
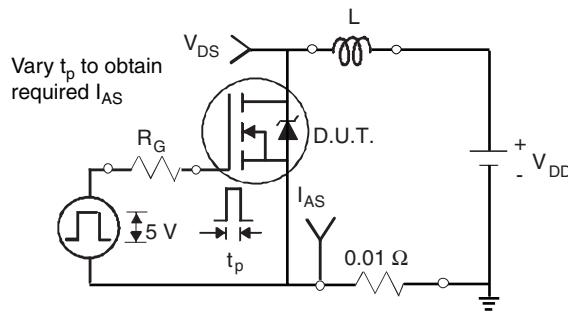
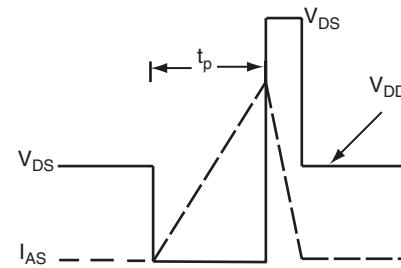


Fig. 8 - Maximum Safe Operating Area


Fig. 9 - Maximum Drain Current vs. Case Temperature

Fig. 10a - Switching Time Test Circuit

Fig. 10b - Switching Time Waveforms

Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

Fig. 12a - Unclamped Inductive Test Circuit

Fig. 12b - Unclamped Inductive Waveforms

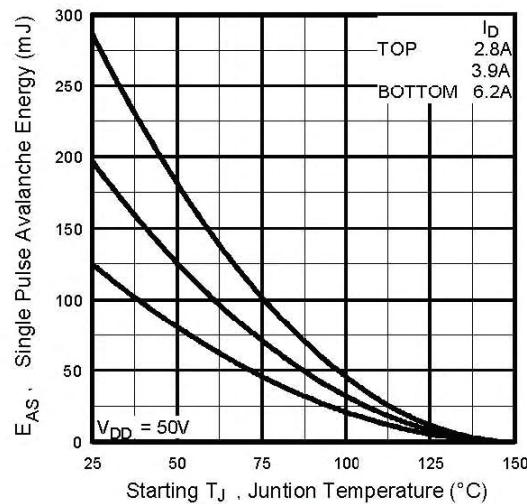


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

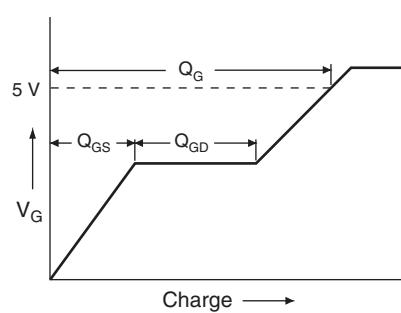


Fig. 13a - Basic Gate Charge Waveform

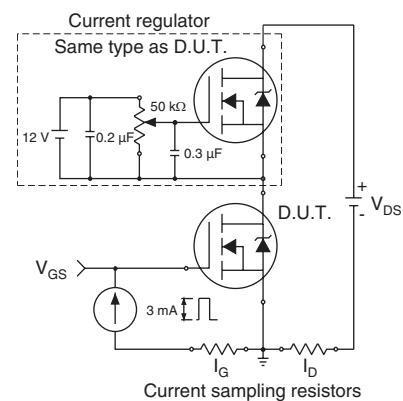
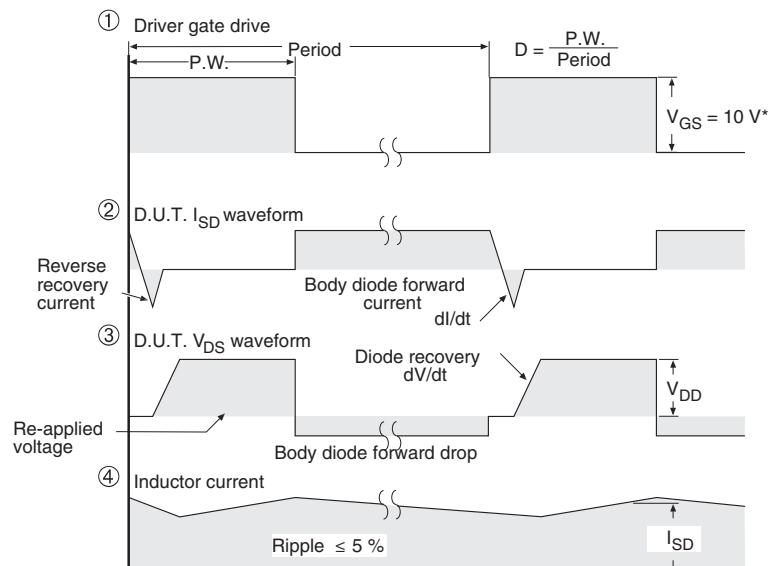
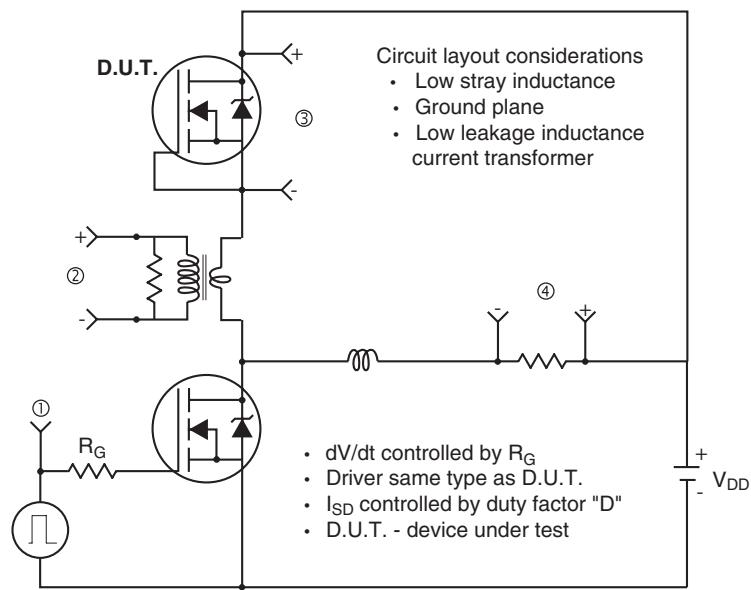


Fig. 13b - Gate Charge Test Circuit

Peak Diode Recovery dV/dt Test Circuit



* $V_{GS} = 5 V$ for logic level devices and 3 V drive devices

Fig. 14 - For N-Channel

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